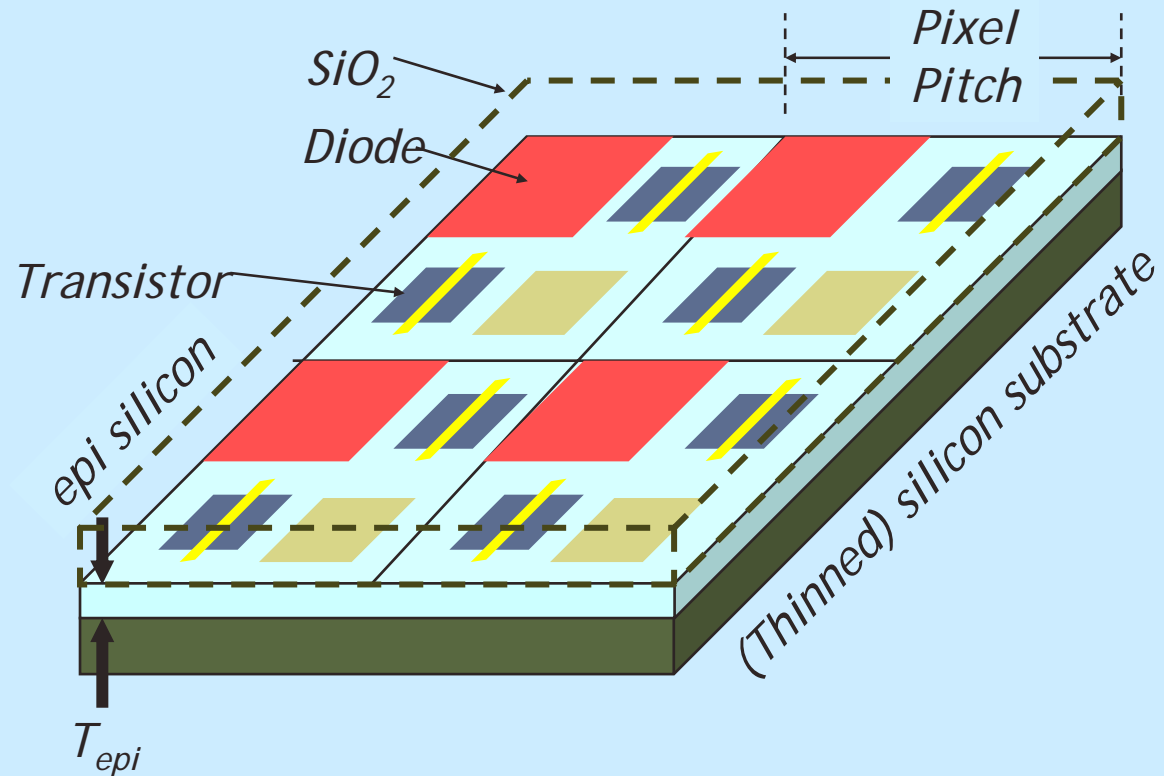


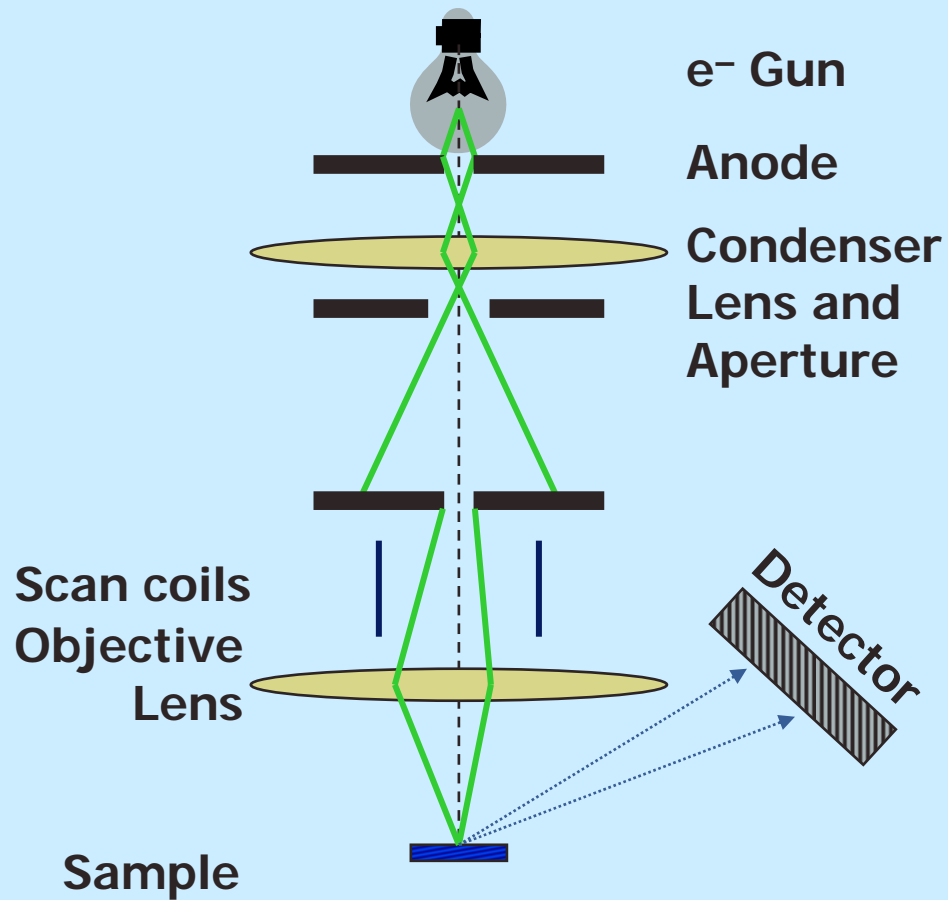
Active Pixel Sensors for Electron Microscopy

P. Denes, JM Bussat – Engineering Division
Z. Lee, V. Radmilovic – National Center for Electron Microscopy
Lawrence Berkeley National Lab

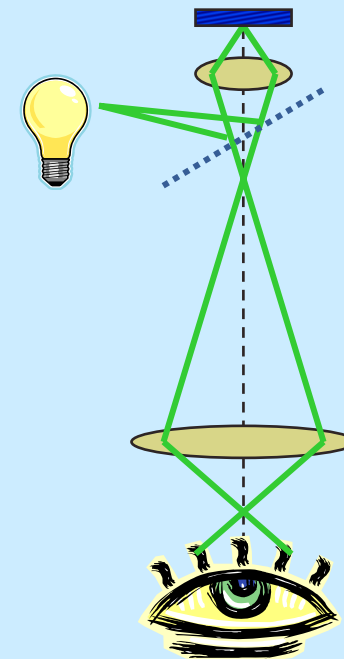
- ◆ Monolithic CMOS Active Pixel Sensors are obvious for Transmission Electron Microscopy
- ◆ Why?
- ◆ Challenges
- ◆ Possibilities



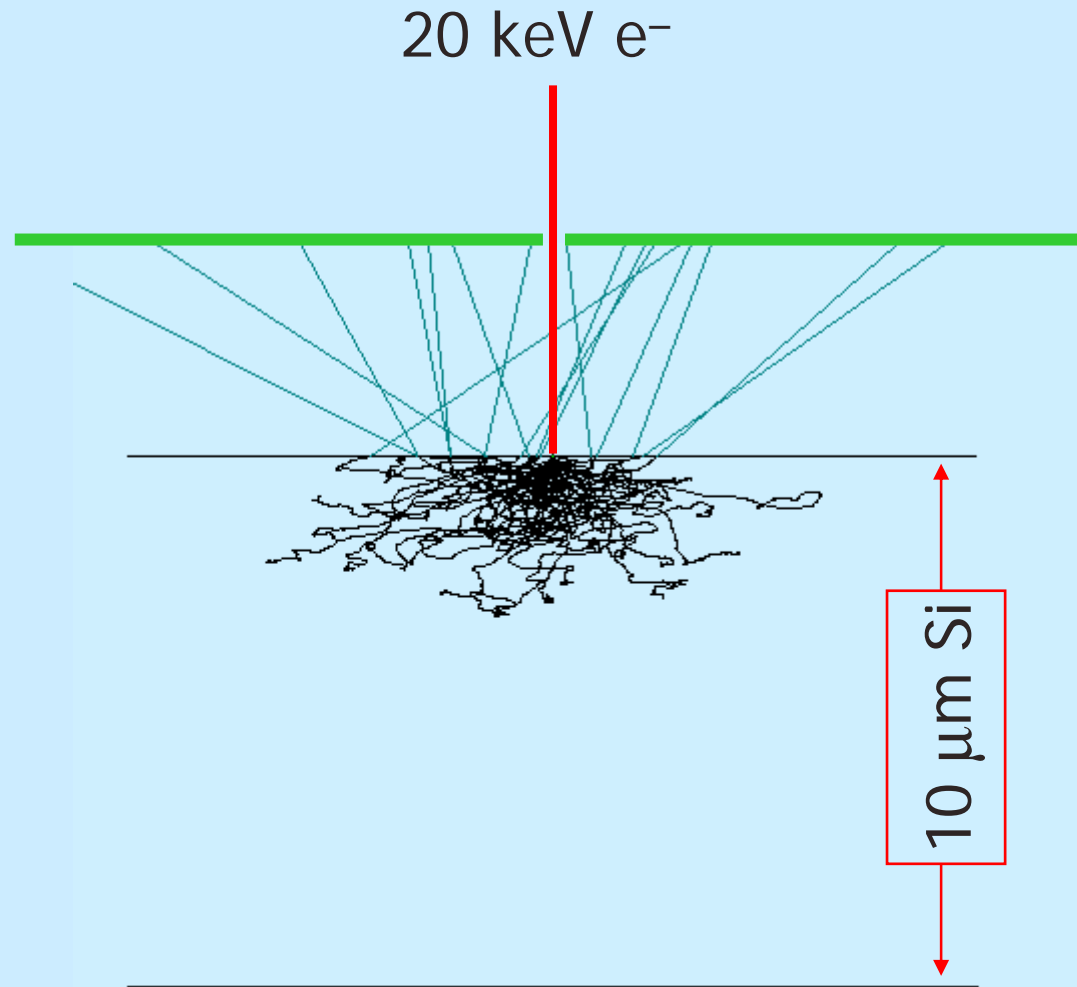
Scanning EM



- ◆ < 30 keV
- ◆ Secondary or backscattered electrons
- ◆ Analogous to metallurgical light microscope

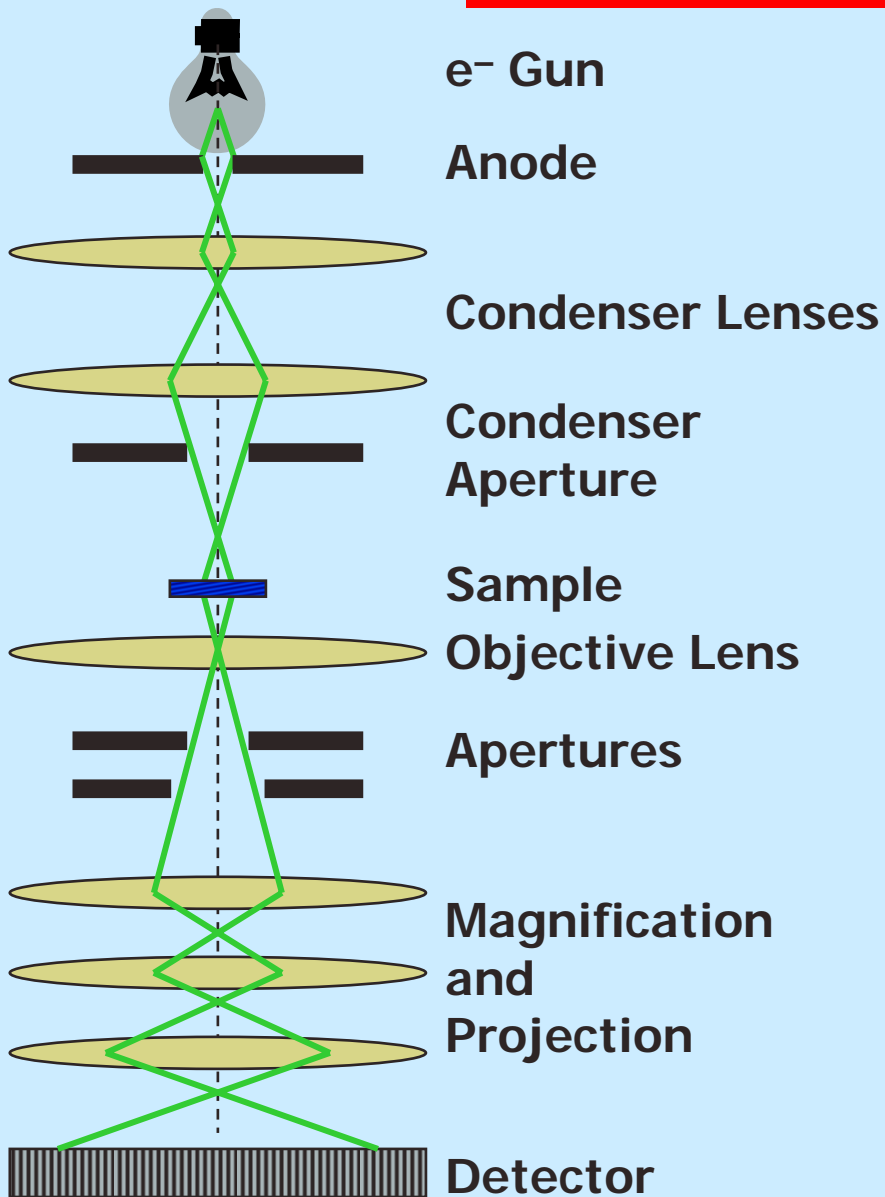


Back-scattered electrons

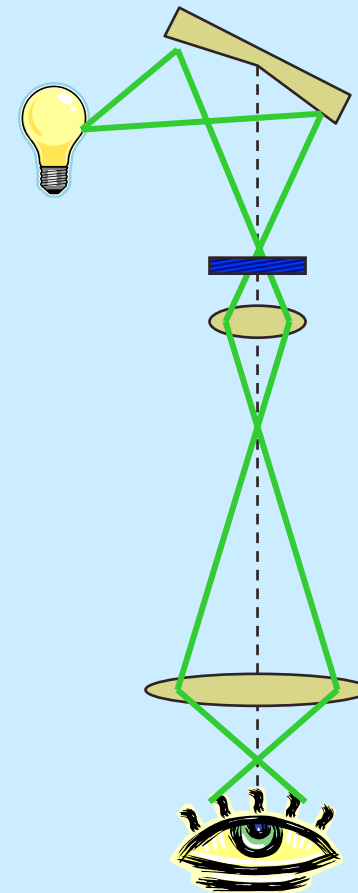


At energies used for microscopy, electrons really scatter!

Transmission EM



- ◆ 100 - 400 keV
- ◆ Transparent (thin) sample
- ◆ Analogous to biological light microscope

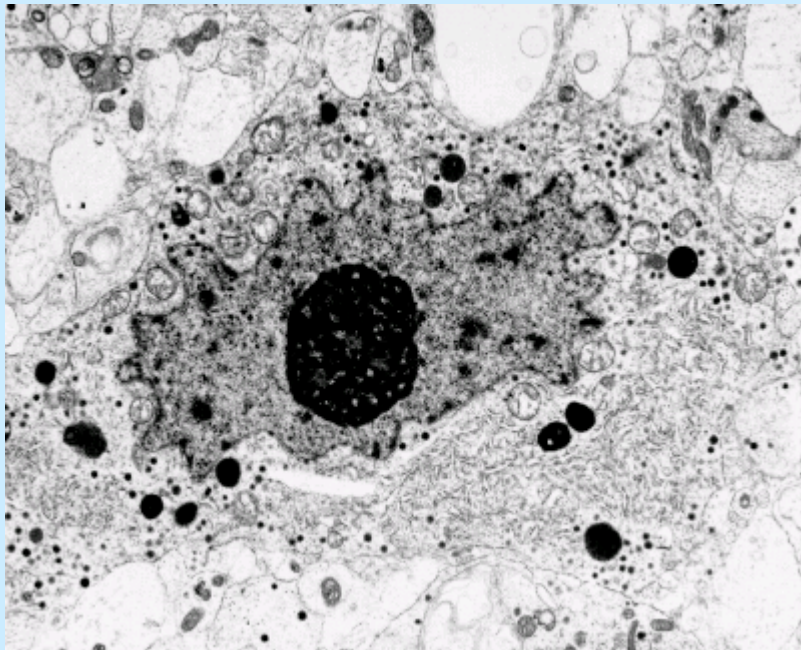


Energy vs. ...

Simple approximation:

- ◆ $P_e(>\theta) \sim (\rho t) (Z^2/A) / E^2\theta^2$
- ◆ $P_i(>\theta) \sim (\rho t) (Z/A) / E^2\theta^2$
- ◆ $P_i(>\theta) / P_e(>\theta) = 1/Z$

- ◆ $A/Z \sim 2$ for all elements
- ◆ $P_e(>\theta) \sim \rho t Z / E^2$
- ◆ Higher $Z \rightarrow$ more scattering
- ◆ Thinner samples or higher energies



Biological samples:

$Z \sim 6$ – stain

(e.g. $\text{UO}_2(\text{CH}_3\text{COO})_2 \cdot 2\text{H}_2\text{O}$)

to increase contrast

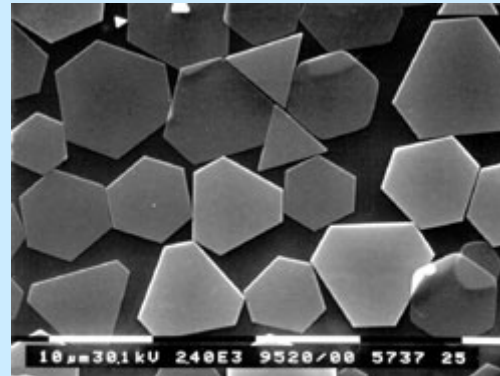
Materials: higher E , but

displacement damage

(e.g. ~ 150 keV in Si)

$$1 \text{ pA/nm}^2 \rightarrow 6 \times 10^{20} \text{ e}^-/\text{cm}^2/\text{s}$$

Traditional High-Performance EM Detectors



Electron micrograph of tabular grain emulsion

AgX + gelatin (emulsion)

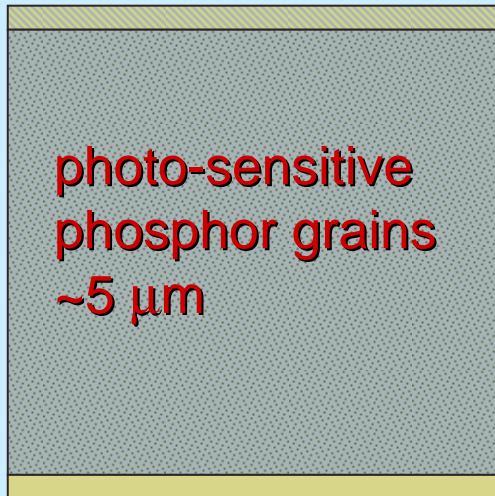
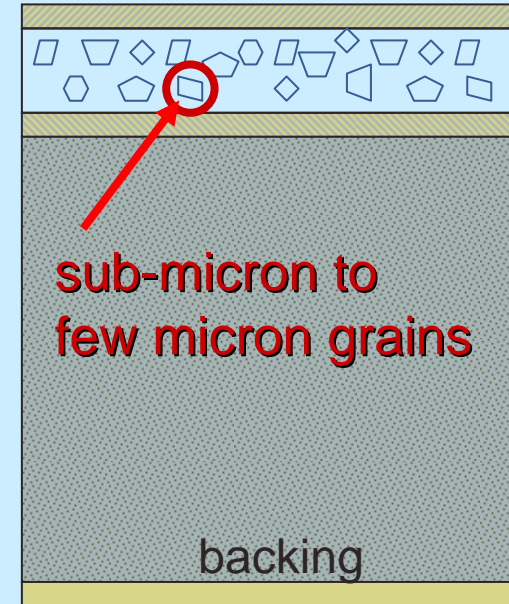
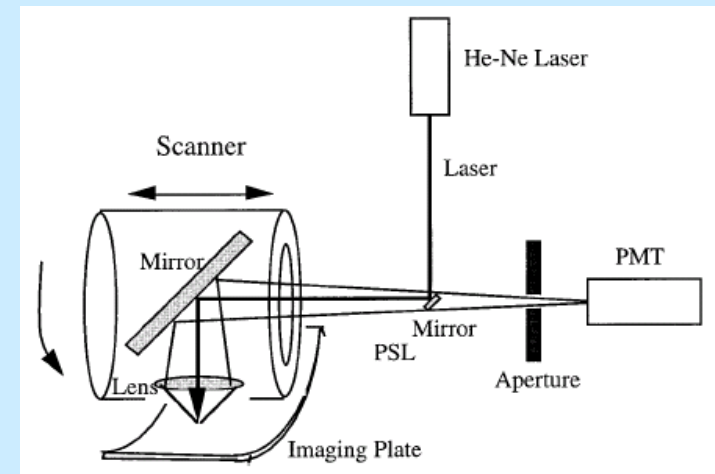
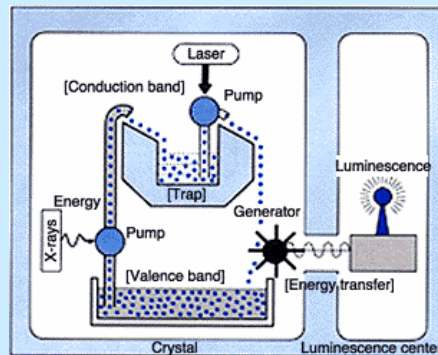
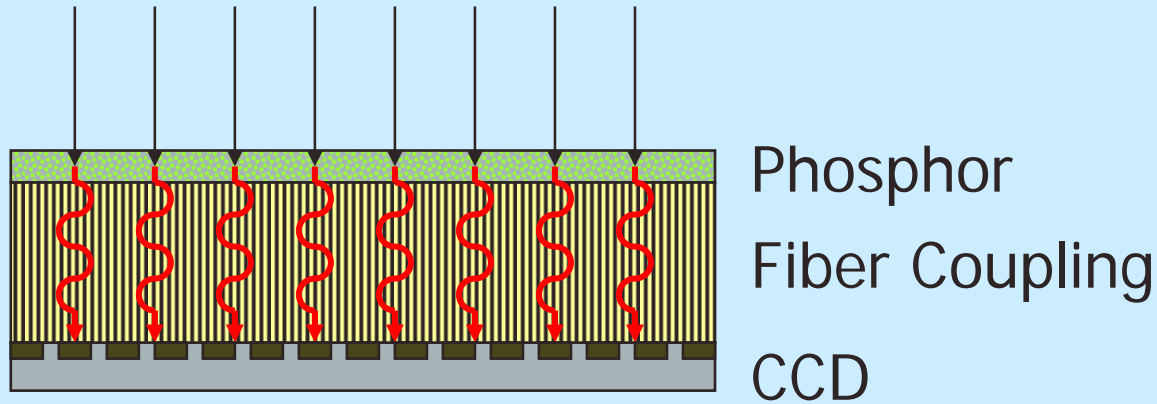


photo-sensitive phosphor grains
~5 μm

“Reusable film”
Scanned by laser
Linear, eraseable



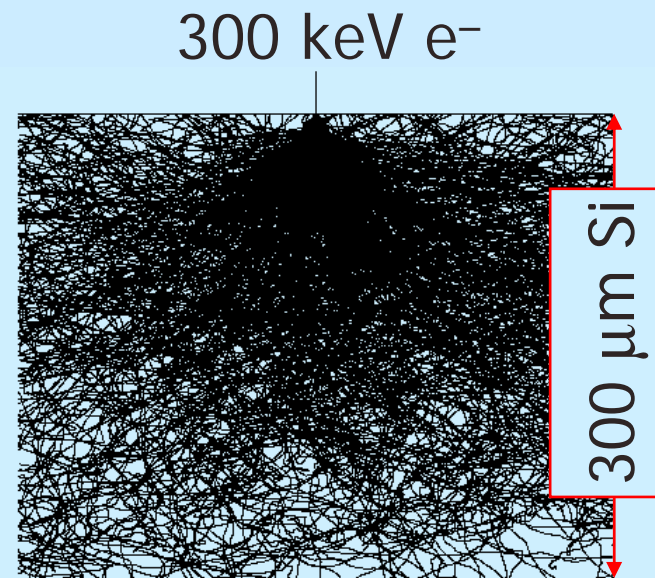
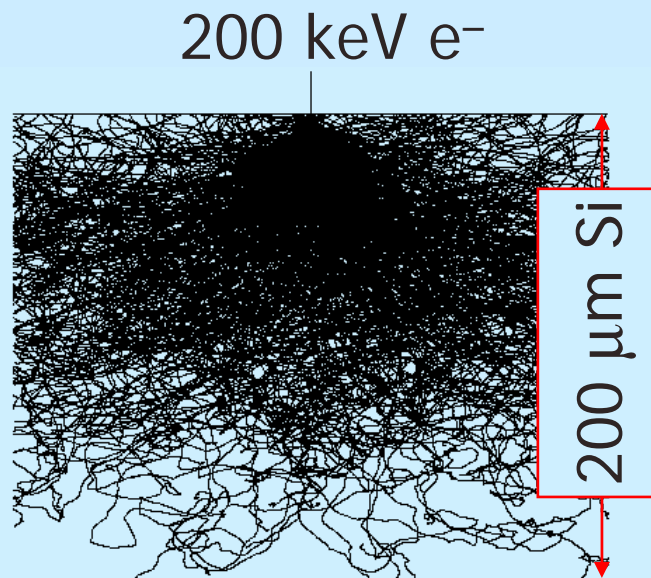
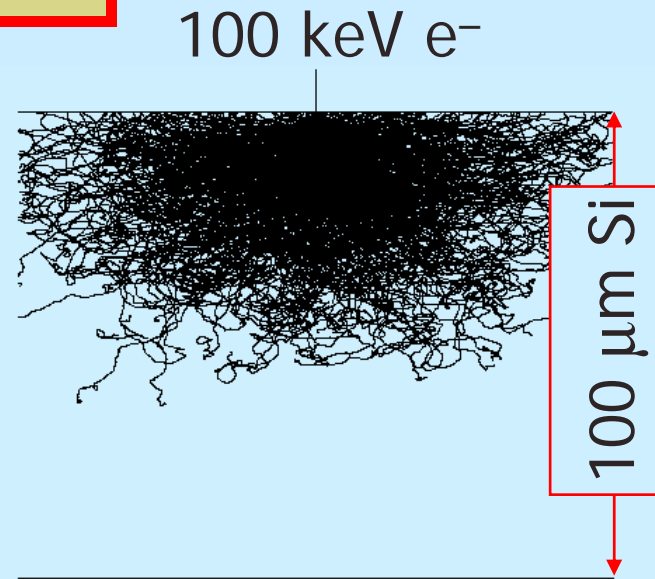
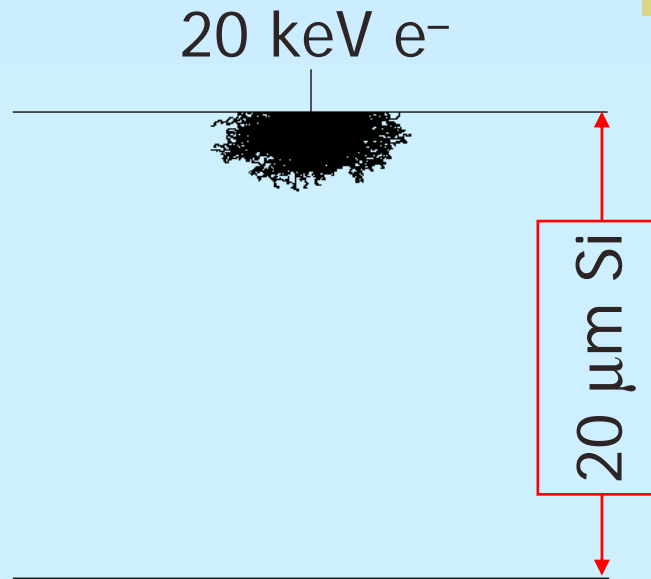
Traditional "Digital" EM Imaging Detector



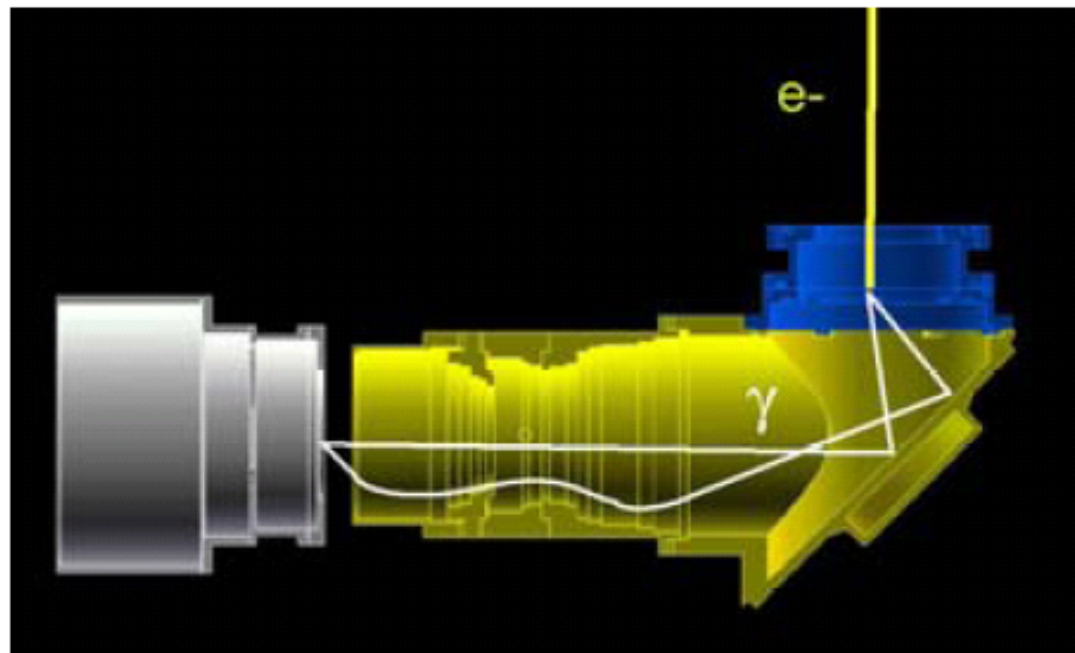
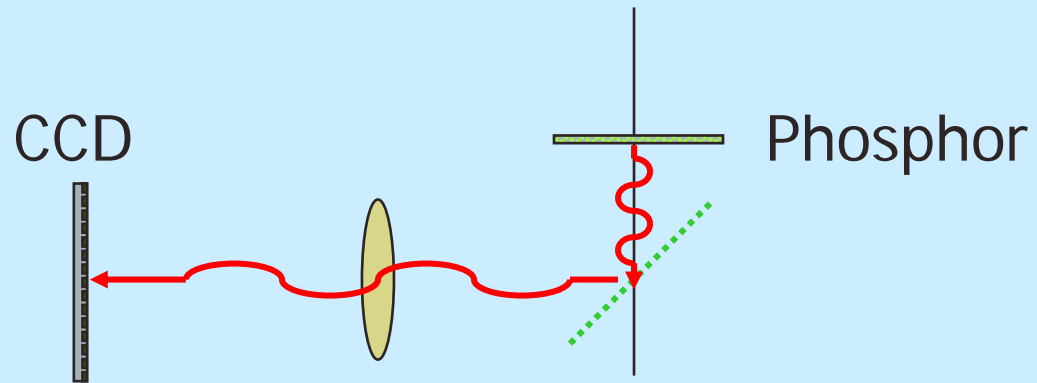
- ◆ $e^- \rightarrow \gamma$ Phosphor must be thin to minimize e^- multiple scattering
- ◆ Photons scatter
- ◆ Electrons scatter
- ◆ $\gamma \rightarrow e^-$ CCD QE



The Problem



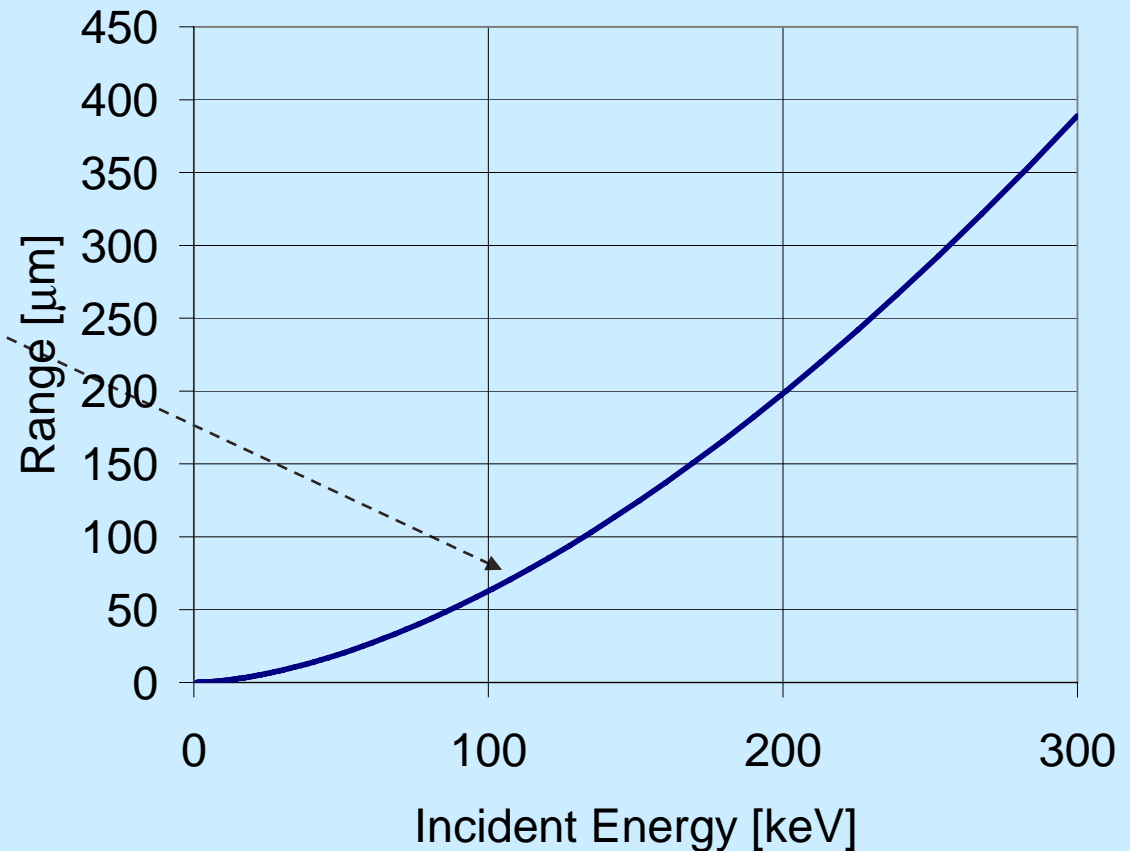
Lens-coupled CCD



In the Past 10+ Years

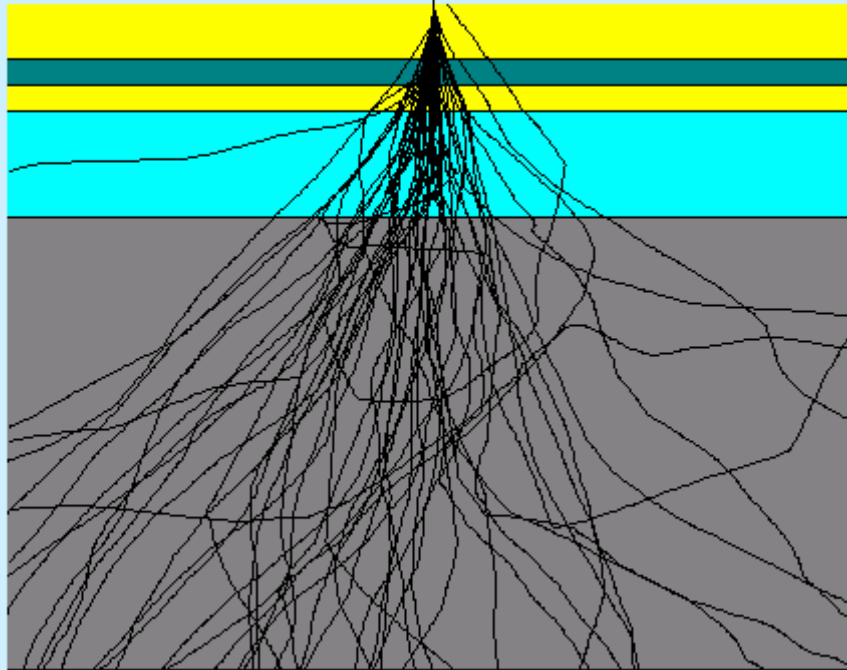
“Direct detection in silicon”

- ◆ Direct detection in CCDs – radiation damage
- ◆ Hybrid pixels
 - ◆ *Fan et al. - 1998*
 - ◆ *Faruqi et al.*
 - ▲ *Medipix at 120 keV*
Pixel size ~ “blob” size
- ◆ CMOS APS



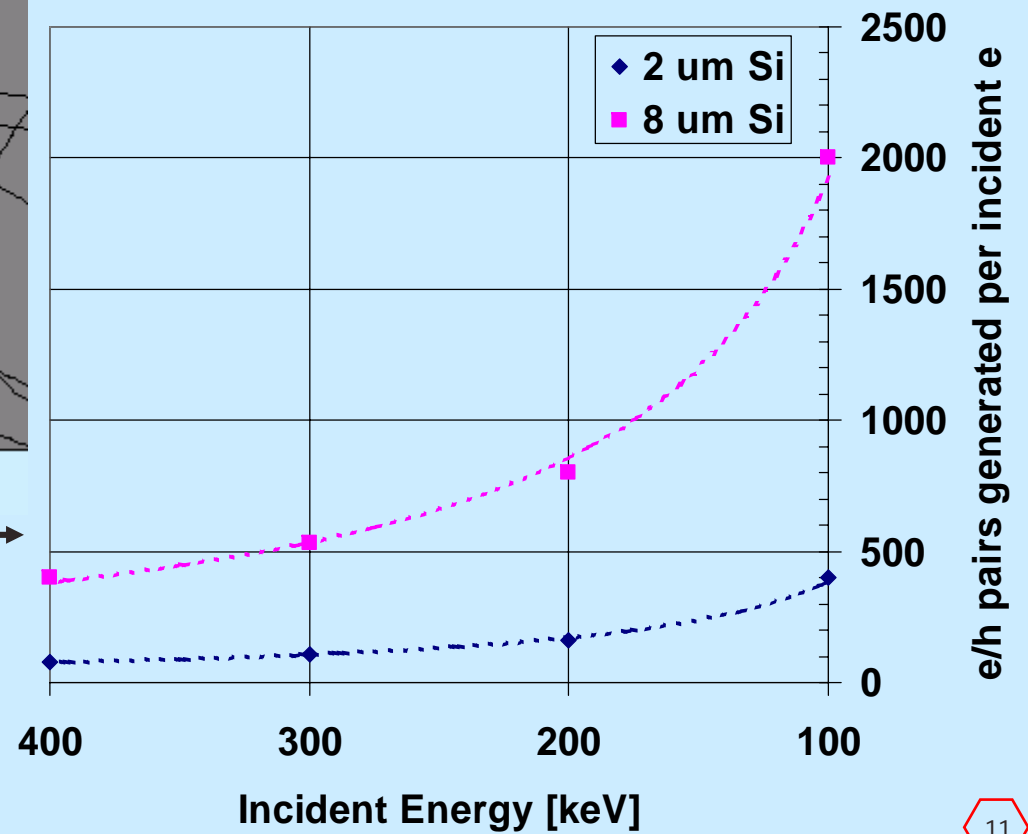
Why APS?

300 keV e⁻

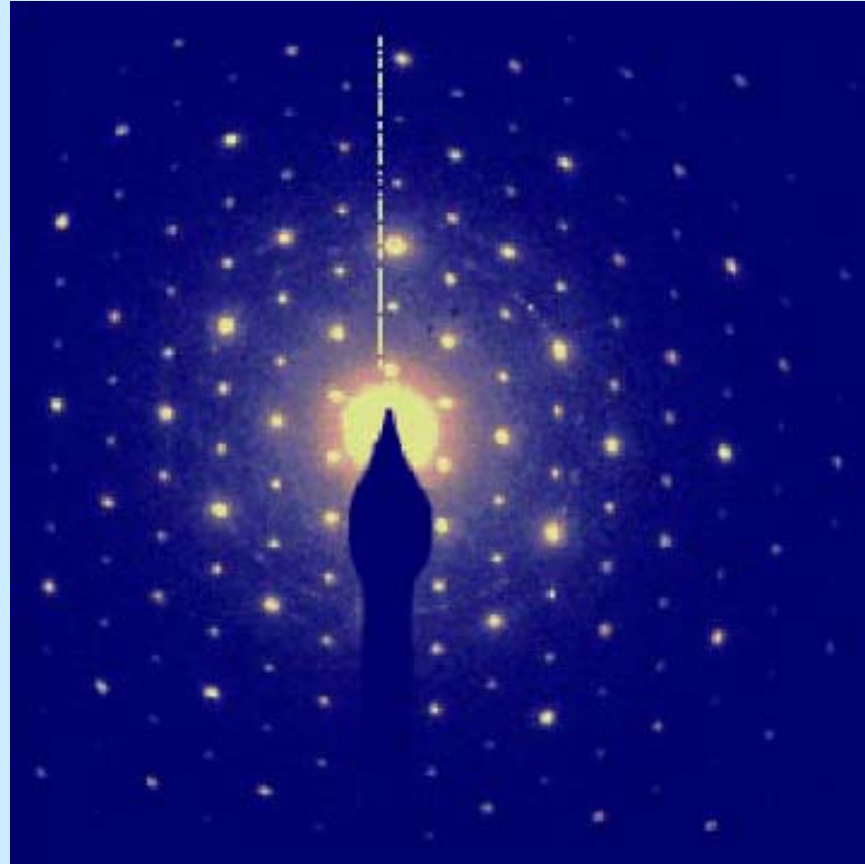


SiO₂ + metal

Si epi



An Example



525 x 525
25 μm pixels
0.5 μm CMOS
from RAL

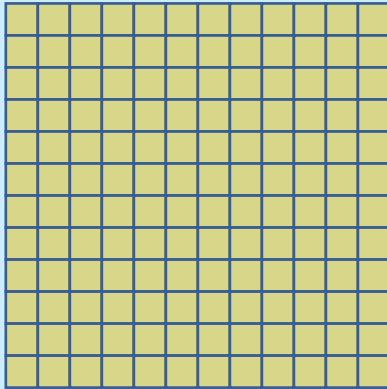
Diffraction pattern from vermiculite

Pros and Cons

	“Digital” [Si]	Film [or I.P.]
◆ Processing	Electronic	Chemical
◆ Linearity	“ideal” $n(e^-) = QE \times n(\gamma)$	non-linear – $n \gamma$ required to flip a grain; thermal fluctuations vs grain size; linear
◆ Resolution	Larger [smaller] pixels	Smaller grains
◆ Dynamic range	CCDs – 16 bits [APS – speed]	Locally, ~4 bits; [16 bits]
◆ MTF	Regular pattern – aliasing	Given by smallest grains, no aliasing
◆ MTF x S/N	Better	Worse; [best – at low rate]

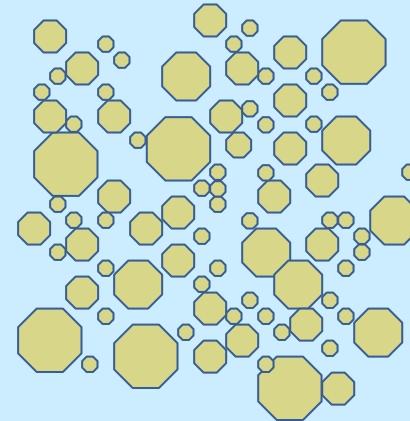
Who Wins?

“Silicon”



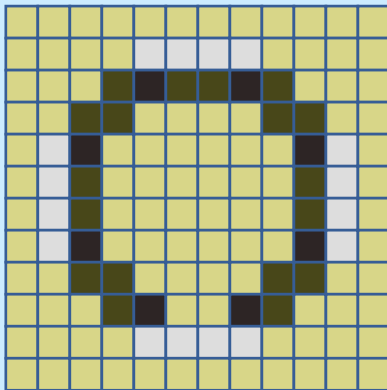
Regular array of pixels
pitch p

Film

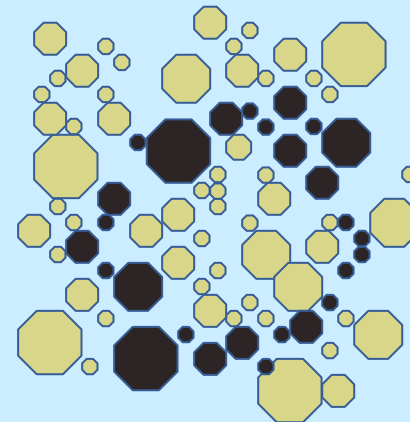
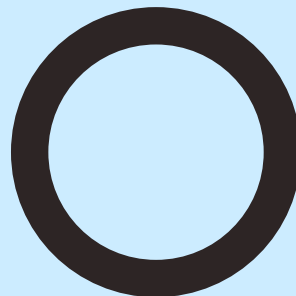


Random collection of
different grain sizes

For now film grains smaller than silicon pixels

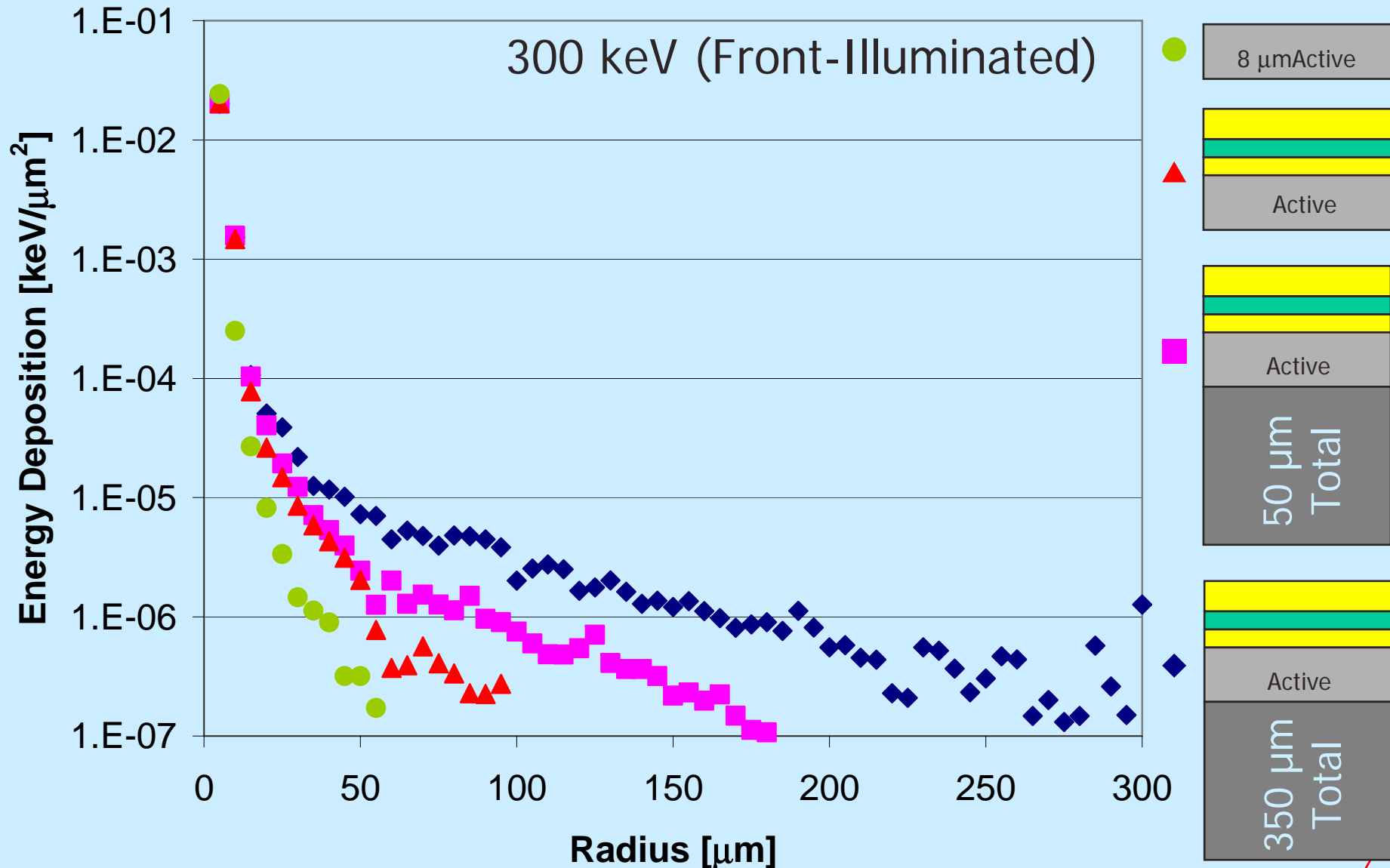


Analog

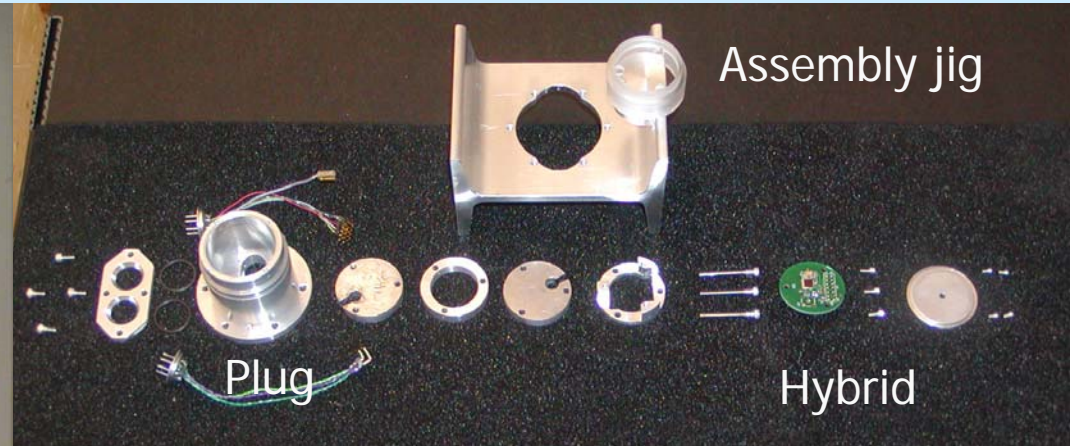


Digital

Some Thinning Helps



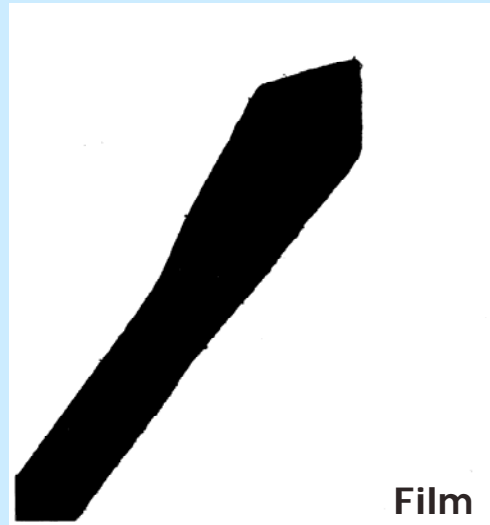
Tests on 200CX at NCEM



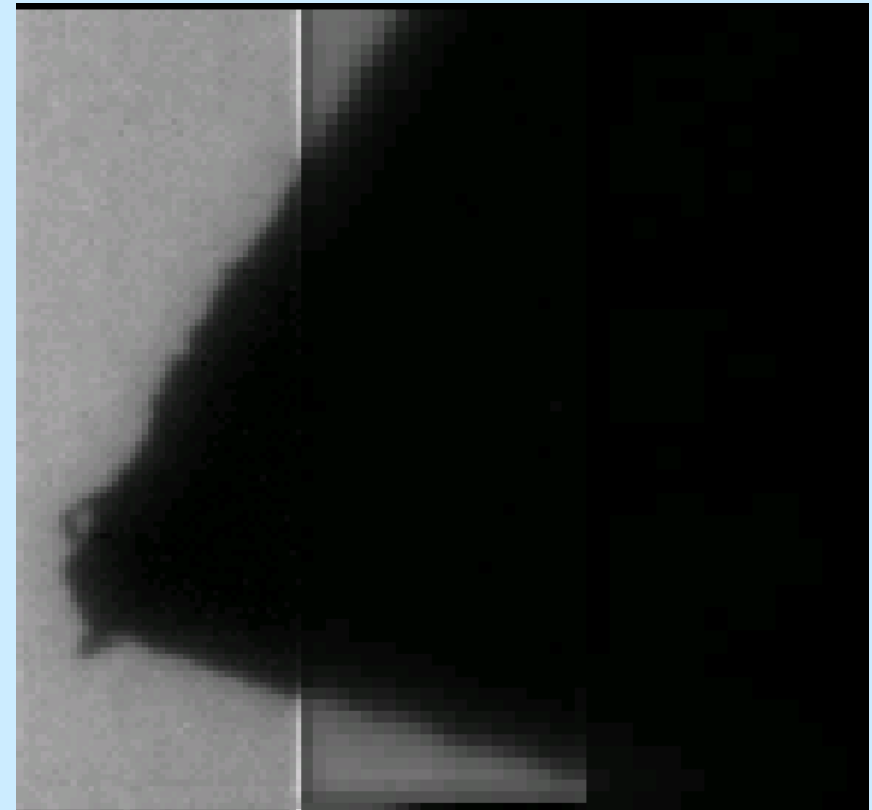
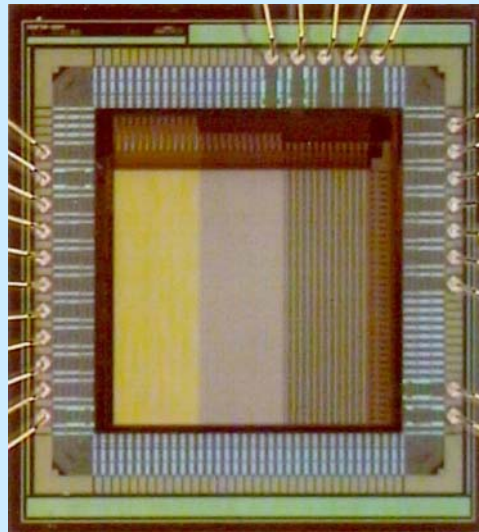
Modified GATAN bright field STEM detector housing at the bottom of the JEOL 200CX TEM

An Example

Beamstop
on 200CX
(imaged at
200 keV)

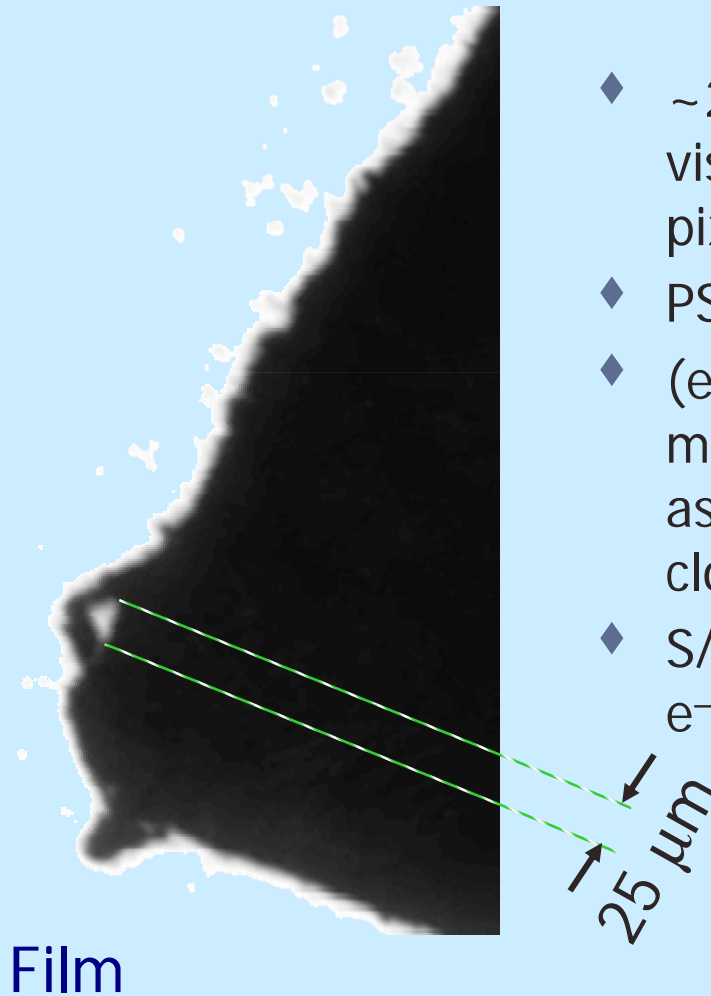
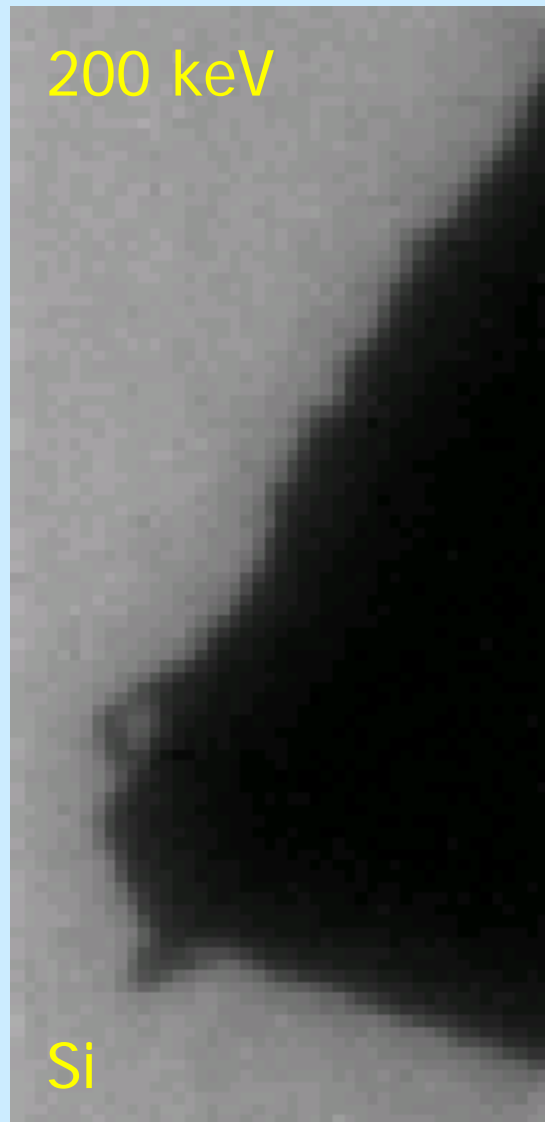


APS in
 $0.35 \mu\text{m}$



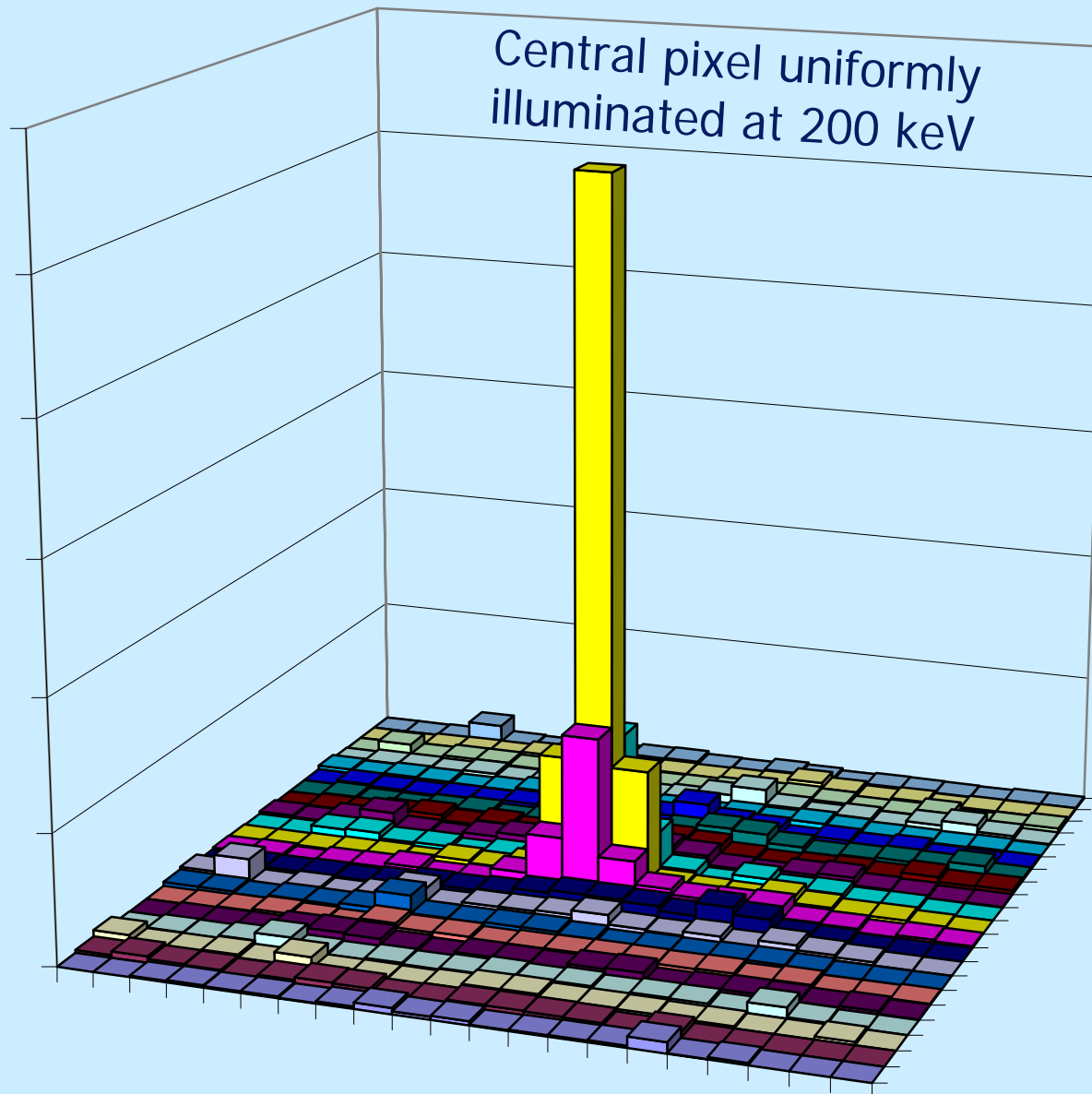
48x144 24x72 12x36
10 μm Pixels 20 μm Pixels 40 μm Pixels

Small Features Visible



- ◆ $\sim 20 \mu\text{m}$ features visible with $10 \mu\text{m}$ pixels
- ◆ PSF $\sim 15 \mu\text{m}$
- ◆ (equiv. MTF at $40\text{-}50 \text{ mm}^{-1} \sim 20\%$ - not as good as film, but close*)
- ◆ S/N $\sim 8.3 \rightarrow$ single e^- sensitivity

vs. Prediction



- ◆ PSF due to e^- multiple scattering at 200 keV $\sim 6 \mu\text{m}$
- ◆ Diffusion dominant

"Specifications"

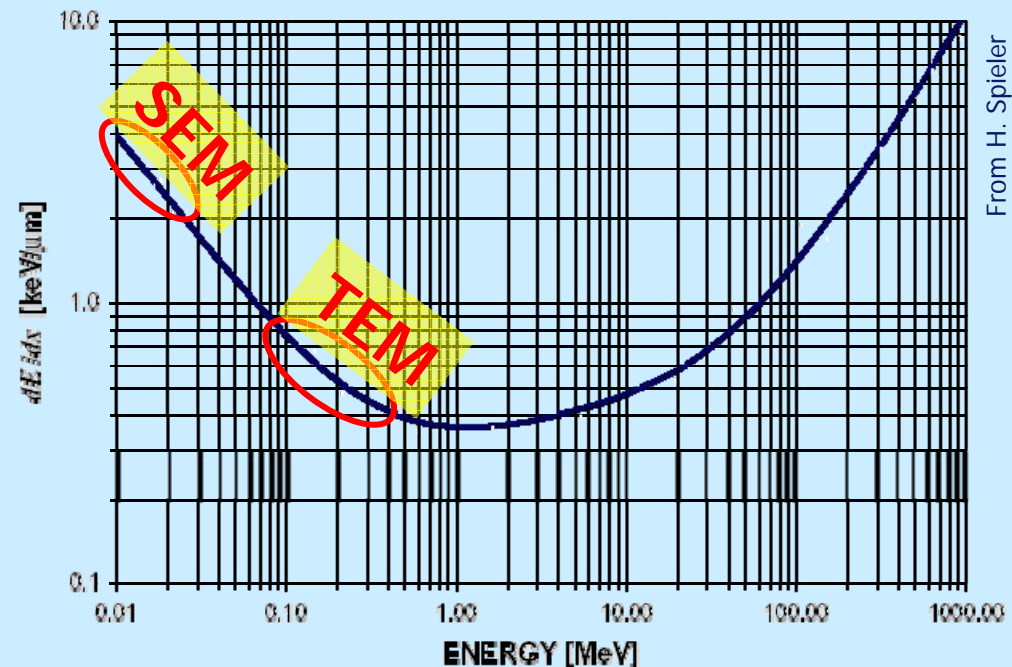
Next-generation materials microscope

Parameter	Spec.	Units	Comment
Incident energy	100-300	keV	
Radiation hardness	300	images/day	min.
	10^5	images/day	desired
	~ 1	year lifetime	
e-/pixel/image	500		"imaging"
	10^5		"diffraction"
Elements	1200^2	pixels	200Å field-of-view with pixel size 0.5/3 Å
PSF	25%		(value at $\frac{1}{2}$ Nyquist)
Resolution	\sqrt{N}		i.e. "shot noise limited"
Full scale	(given by frame rate)		e-/pixel/s x frame rate
Frame rate	<10	ms	

Biology not so different, except desire to have ∞ pixels

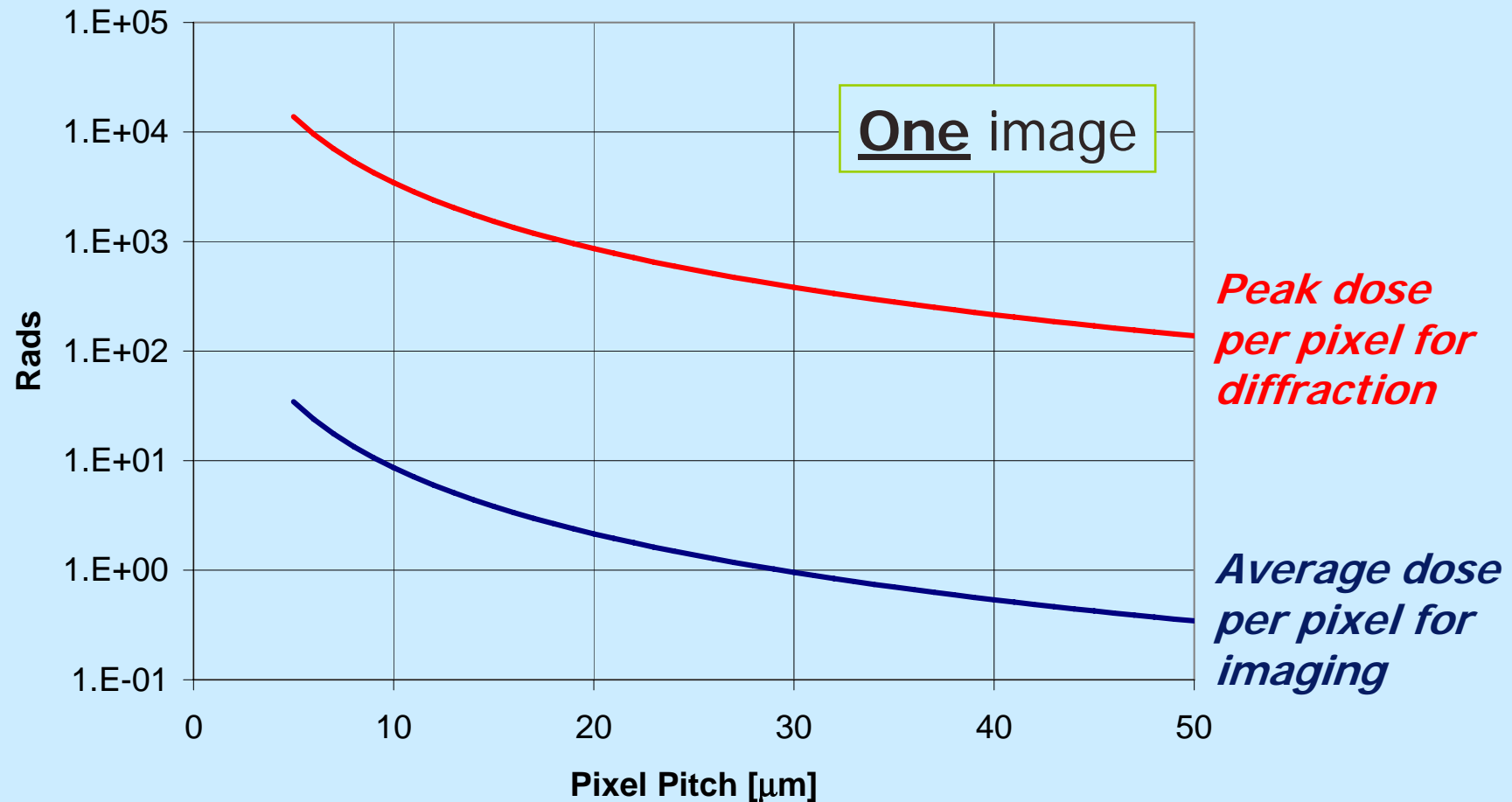
Challenges

- ◆ High S/N is desirable, but need to accommodate 100 (bio) 500 (materials) 10^5 (diffraction) primary e^- per pixel per image (readout rate dependent)
- ◆ “Resolution” is not the issue (optics set field of view), just number of pixels
- ◆ Readout speed helps in all applications
- ◆ **Radiation damage!**
- ◆ Region of interest:
1 – few \times M.I.



Radiation Damage

- ◆ Displacement damage not significant
- ◆ Ionizing dose not negligible



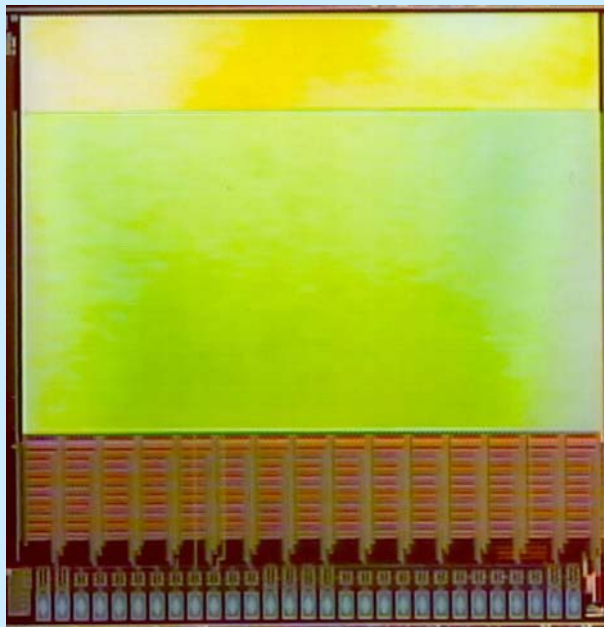
What We've Been Up To

Two 0.25 μm CMOS Prototypes (2005)

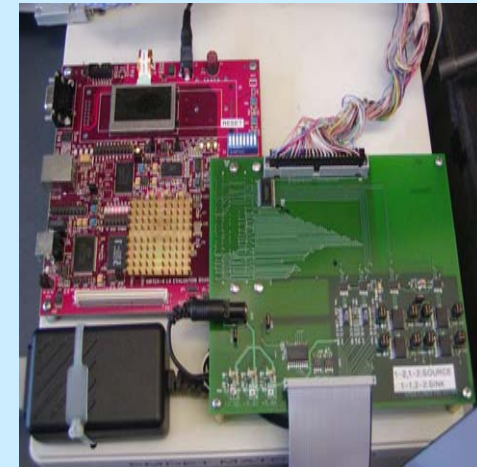


19 μm pixels
in-pixel CDS

6 μm pixels



on-chip
digitizers

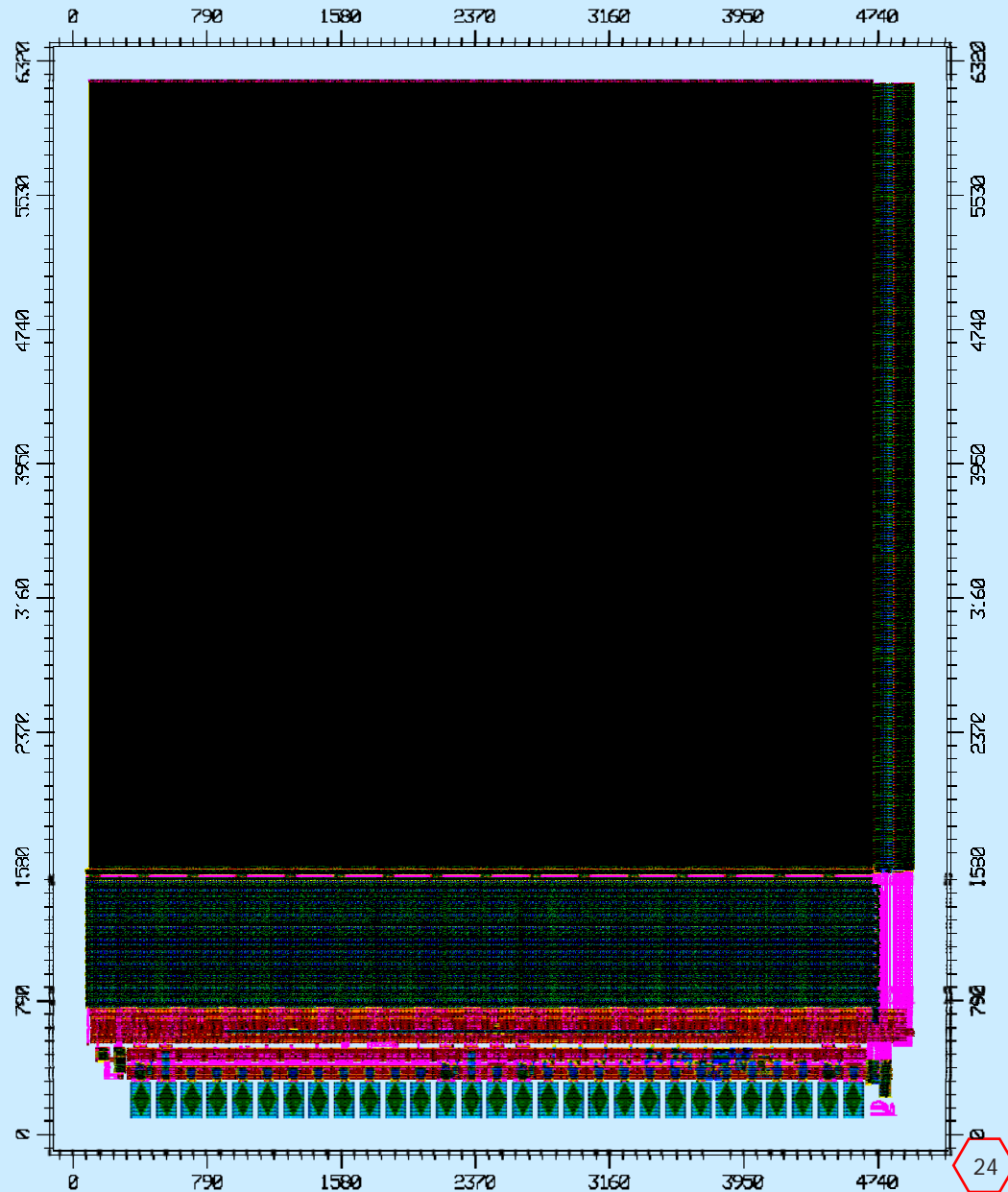


Readout System

← 5 mm →

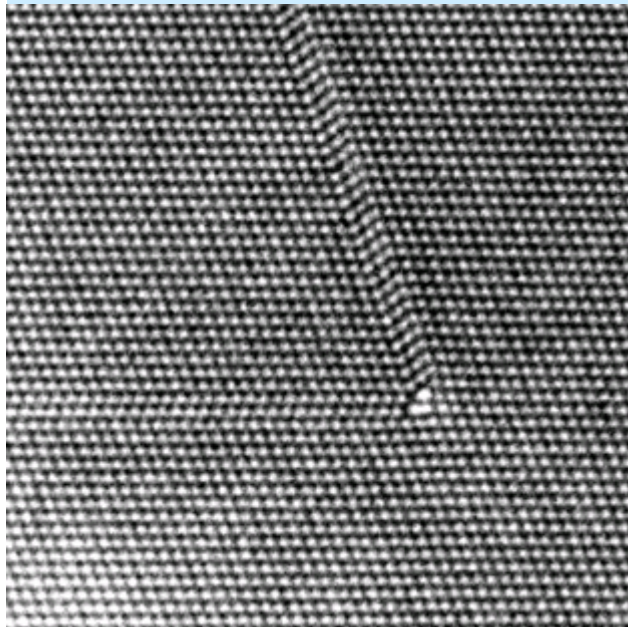
Now in Fab

- ◆ 9 μm pixels
- ◆ 512 x 512
- ◆ Adjustable gain
- ◆ Same backend (digitizers and readout)
- ◆ Prototype for 2k x 2k



What This Achieves

- ◆ Unprecedented speed
 - ◆ *Visualize catalysis*
 - ◆ *Reduce beam-induced motion of biological samples*
- ◆ High DQE
 - ◆ *Good single e^- sensitivity and good PSF*
 - ◆ *DQE = 1 if variance of input signal faithfully transmitted*
- ◆ Spatial resolution better than fiber-coupled phosphor + CCD
 - ◆ *Eventually approach film*
- ◆ Uniformity and linearity
- ◆ Radiation hardness requirement not negligible



Atomic resolution image of stacking faults in Gold

(An) Ultimate Goal

